

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.00583	100.0	0.28628
	Pure metal	Aluminium (Al)	7429-90-5	0.38857	100.0	19.08522
			Subtotal	0.3944	200	19.3715
Solder Paste	Lead alloy	Tin (Sn)	7440-31-5	0.01934	5.0	0.95
	Lead alloy	Lead (Pb)	7439-92-1	0.32881	85.0	16.15
	Lead alloy	Antimony (Sb)	7440-36-0	0.03868	10.0	1.9
			Subtotal	0.38683	100	19
Die		Silicon (Si)	7440-21-3	0.43305	100.0	21.26987
			Subtotal	0.43305	100	21.26987
Solder Paste	Pure metal	Tin (Sn)	7440-31-5	0.06006	5.0	2.95
	Pure metal	Silver (Ag)	7440-22-4	0.03003	2.5	1.475
	Pure metal	Lead (Pb)	7439-92-1	1.11114	92.5	54.575
			Subtotal	1.20123	100	59
Isolator	Aluminium alloy	Aluminium Trioxide (Al2O3)	1344-28-1	3.82764	100.0	188
			Subtotal	3.82764	100	188
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00513	0.03	0.252
	Copper alloy	Iron (Fe)	7439-89-6	0.01881	0.11	0.924
	Copper alloy	Copper (Cu)	7440-50-8	17.07486	99.84	838.656
	Copper alloy	Silver (Ag)	7440-22-4	0.00342	0.02	0.168
	Copper alloy	Phosphorous (P)	7723-14-0	0.01636	0.03	0.8034
	Copper alloy	Iron (Fe)	7439-89-6	0.05998	0.11	2.9458
	Copper alloy	Copper (Cu)	7440-50-8	54.44719	99.86	2674.2508
			Subtotal	71.62575	200	3518
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.06108	100.0	3
			Subtotal	0.06108	100	3
Mould Compound	polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	0.35312	1.6	17.344
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.43455	6.5	70.46
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	2.8691	13.0	140.92
	Filler	Silica fused	60676-86-0	17.21461	78.0	845.52
	Carbon Black	Carbon black	1333-86-4	0.15449	0.7	7.588
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.04414	0.2	2.168
			Subtotal	22.07001	100	1084
			Total	99.99999	100	4911.64137

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